

Sensitive and Standard SCRs, 12A

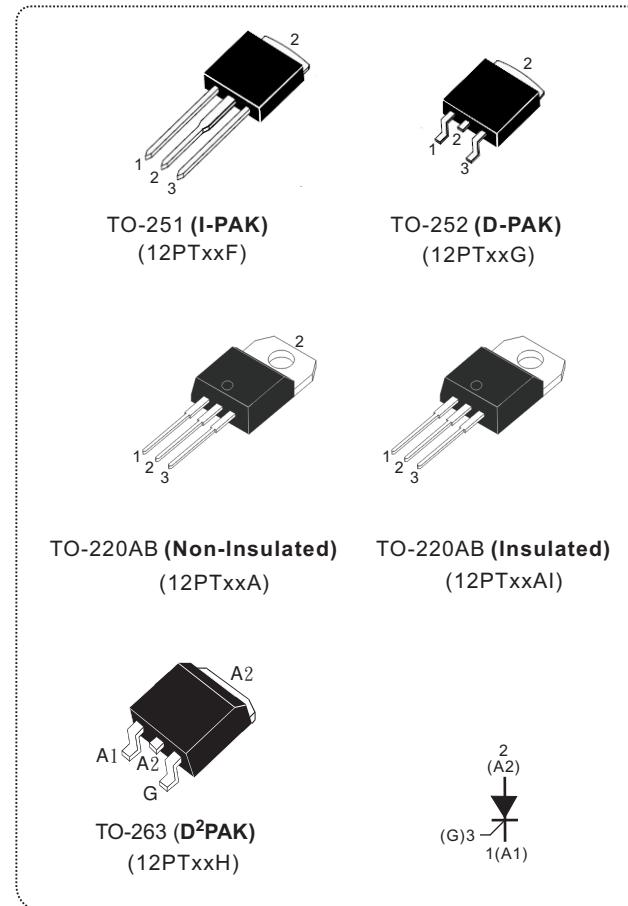
Main Features

Symbol	Value	Unit
$I_{T(RMS)}$	12	A
V_{DRM}/V_{RRM}	600 to 1000	V
I_{GT}	0.2 to 15	mA

DESCRIPTION

Available either in sensitive or standard gate triggering levels, the 12A SCR series is suitable to fit all modes of control found in applications such as overvoltage crowbar protection, motor control circuits in power tools and kitchen aids, inrush current limiting circuits, capacitive discharge ignition and voltage regulation circuits.

Available in through-hole or surface-mount packages, they provide an optimized performance in a limited space.



ABSOLUTE MAXIMUM RATINGS

PARAMETER	SYMBOL	TEST CONDITIONS		VALUE	UNIT
RMS on-state current full sine wave (180° conduction angle)	$I_{T(RMS)}$	TO-251/TO-252/TO-220AB/TO-263	$T_c=105^\circ C$	12	A
		TO-220AB insulated	$T_c=90^\circ C$		
Average on-state current (180° conduction angle)	$I_{T(AV)}$	TO-251/TO-252/TO-220AB/TO-263	$T_c=105^\circ C$	8	A
		TO-220AB insulated	$T_c=90^\circ C$		
Non repetitive surge peak on-state current (full cycle, T_j initial = 25°C)	I_{TSM}	$F=50$ Hz	$t=20$ ms	140	A
		$F=60$ Hz	$t=16.7$ ms	145	
I^2t Value for fusing	I^2t	$t_p=10$ ms		98	A^2s
Critical rate of rise of on-state current $I_G = 2xI_{GT}$, $t \leq 100$ ns	dI/dt	$F=60$ Hz	$T_j = 125^\circ C$	50	$A/\mu s$
Peak gate current	I_{GM}	$T_p = 20$ μs	$T_j = 125^\circ C$	4	A
Average gate power dissipation	$P_{G(AV)}$	$T_j = 125^\circ C$		1	W
Storage temperature range	T_{stg}			- 40 to + 150	$^\circ C$
Operating junction temperature range	T_j			- 40 to + 125	

STANDARD ELECTRICAL SPECIFICATIONS		$(T_j = 25 \text{ }^{\circ}\text{C, unless otherwise specified})$				
SYMBOL	TEST CONDITIONS	12PTxxxx		Unit		
		T	-			
I_{GT}	$V_D = 12 \text{ V}, R_L = 33\Omega$	Min.	0.5	2	mA	
V_{GT}		Max.	5	15		
V_{GD}	$V_D = V_{DRM}, R_L = 3.3\text{K}\Omega$	$T_j = 125 \text{ }^{\circ}\text{C}$	Min.	0.2	V	
I_H	$I_T = 500 \text{ mA, gate open}$		Max.	15	30	mA
I_L	$I_G = 1.2 I_{GT}$		Max.	30	60	mA
dV/dt	$V_D = 67\% V_{DRM}, \text{gate open}$	$T_j = 125 \text{ }^{\circ}\text{C}$	Min.	40	200	V/ μ s
V_{TM}	$I_{TM} = 24\text{A}, t_p = 380 \text{ }\mu\text{s}$	$T_j = 25 \text{ }^{\circ}\text{C}$	Max.	1.6		V
V_{to}	Threshold voltage	$T_j = 125 \text{ }^{\circ}\text{C}$	Max.	0.85		V
R_d	Dynamic resistance	$T_j = 125 \text{ }^{\circ}\text{C}$	Max.	30		m Ω
I_{DRM}	$V_{DRM} = V_{RRM}$	$T_j = 25 \text{ }^{\circ}\text{C}$	Max.	5	μ A	
I_{RRM}		$T_j = 125 \text{ }^{\circ}\text{C}$		2		mA

SENSITIVE ELECTRICAL CHARACTERISTICS		$(T_j = 25 \text{ }^{\circ}\text{C, unless otherwise specified})$				
SYMBOL	TEST CONDITIONS	12PTxxxx-S		Unit		
I_{GT}	$V_D = 12 \text{ V}, R_L = 140\Omega$	Max.	200		μ A	
V_{GT}		Max.	0.8		V	
V_{GD}	$V_D = V_{DRM}, R_L = 3.3\text{K}\Omega, R_{GK}=220\Omega$	$T_j = 125 \text{ }^{\circ}\text{C}$	Min.	0.1	V	
V_{RG}	$I_{RG} = 10 \text{ }\mu\text{A}$		Min.	8	V	
I_H	$I_T = 50 \text{ mA}, R_{GK} = 1 \text{ K}\Omega$		Max.	5	mA	
I_L	$I_G = 1 \text{ mA}, R_{GK} = 1 \text{ K}\Omega$		Max.	6	mA	
dV/dt	$V_D = 67\% V_{DRM}, R_{GK} = 220\Omega$	$T_j = 125 \text{ }^{\circ}\text{C}$	Min.	5	V/ μ s	
V_{TM}	$I_{TM} = 24\text{A}, t_p = 380 \text{ }\mu\text{s}$	$T_j = 25 \text{ }^{\circ}\text{C}$	Max.	1.6	V	
V_{to}	Threshold voltage	$T_j = 125 \text{ }^{\circ}\text{C}$	Max.	0.85	V	
R_d	Dynamic resistance	$T_j = 125 \text{ }^{\circ}\text{C}$	Max.	30	m Ω	
I_{DRM}	$V_{DRM} = V_{RRM}, R_{GK} = 220\Omega$	$T_j = 25 \text{ }^{\circ}\text{C}$	Max.	5	μ A	
I_{RRM}		$T_j = 125 \text{ }^{\circ}\text{C}$		2		mA

THERMAL RESISTANCE					
SYMBOL	Parameter			VALUE	UNIT
$R_{th(j-c)}$	Junction to case (DC)		IPAK/DPAK/TO-220AB/TO-263	1.3	°C/W
			TO-220AB insulated	4.6	
$R_{th(j-a)}$	Junction to ambient (DC)	$S = 0.5 \text{ cm}^2$	D-PAK	70	°C/W
		$S = 1 \text{ cm}^2$	D ² PAK	45	
			I-PAK	100	
			TO-220AB, TO-220AB insulated	60	

S=Copper surface under tab

PRODUCT SELECTOR

PART NUMBER	VOLTAGE (xx)			SENSITIVITY	PACKAGE
	600 V	800 V	1000 V		
12PTxxA-S/12PTxxAI-S	V	V	V	200 μ A	TO-220AB
12PTxxA-T/12PTxxAI-T	V	V	V	0.5~5 mA	TO-220AB
12PTxxA/12PTxxAI	V	V	V	2~15 mA	TO-220AB
12PTxxF-S	V	V	V	200 μ A	I-PAK
12PTxxF-T	V	V	V	0.5~5 mA	I-PAK
12PTxxF	V	V	V	2~15 mA	I-PAK
12PTxxG-S	V	V	V	200 μ A	D-PAK
12PTxxG-T	V	V	V	0.5~5 mA	D-PAK
12PTxxG	V	V	V	2~15 mA	D-PAK
12PTxxH-S	V	V	V	20 μ A	D ² -PAK
12PTxxH-T	V	V	V	0.5~5 mA	D ² -PAK
12PTxxH	V	V	V	2~15 mA	D ² -PAK

ORDERING INFORMATION

ORDERING TYPE	MARKING	PACKAGE	WEIGHT	BASE Q'TY	DELIVERY MODE
12PTxxA-y	12PTxxA-y	TO-220AB	2.0g	50	Tube
12PTxxAI-y	12PTxxAI-y	TO-220AB (insulated)	2.3g	50	Tube
12PTxxF-y	12PTxxF-y	TO-251(I-PAK)	0.40g	80	Tube
12PTxxG-y	12PTxxG-y	TO-252(D-PAK)	0.38g	80	Tube
12PTxxH-y	12PTxxH-y	TO-263(D ² -PAK)	2.0g	50	Tube

Note: xx = voltage, y = sensitivity

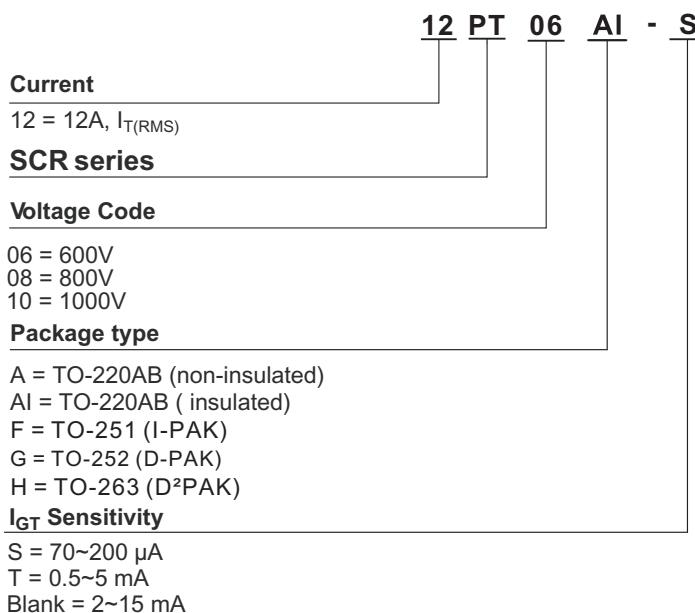
ORDERING INFORMATION SCHEME


Fig.1 Maximum average power dissipation versus average on-state current

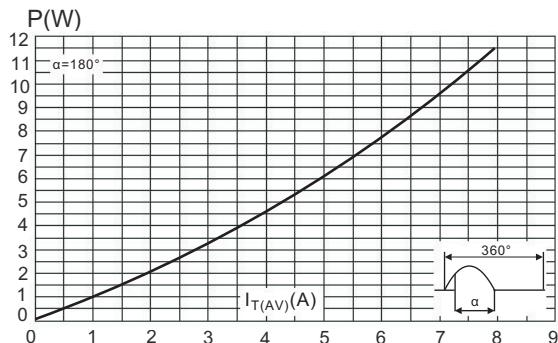


Fig.3 Average and DC on-state current versus ambient temperature (DPAK)

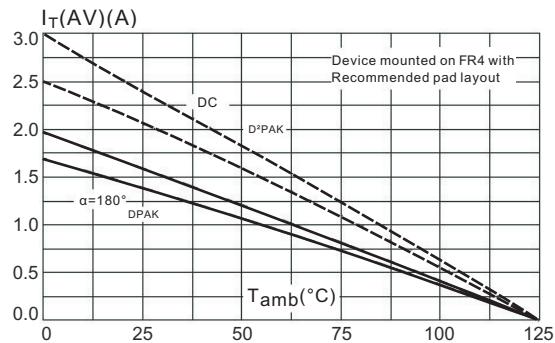


Fig.5 Relative variation of thermal impedance Junction to ambient versus pulse duration (DANK)

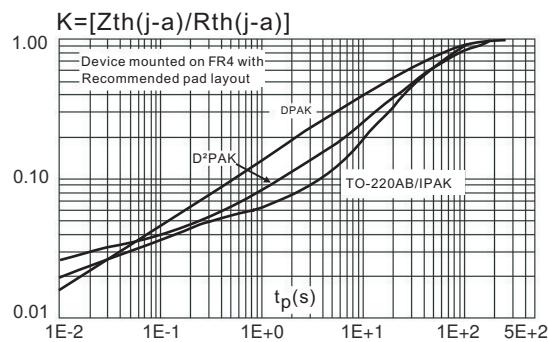


Fig.2 Average and DC on-state current versus case temperature

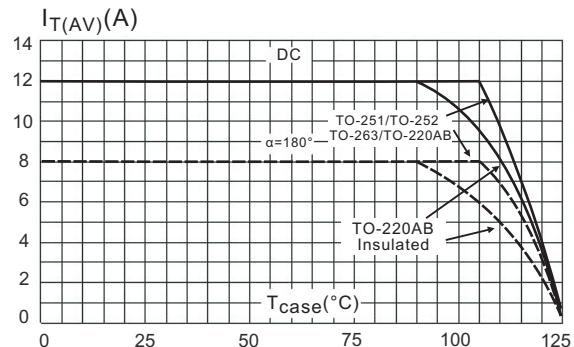


Fig.4 Relative variation of thermal impedance junction to case versus pulse duration

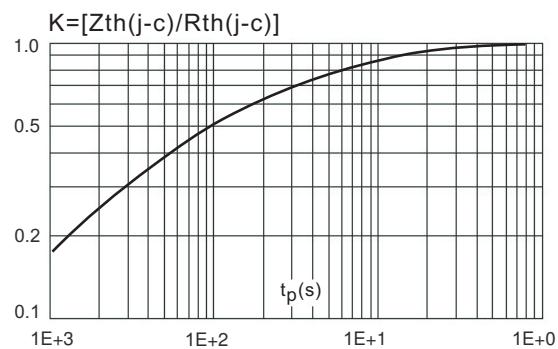


Fig.6 Relative variation of gate trigger and holding current versus junction temperature for $I_{GT}=200\mu A$

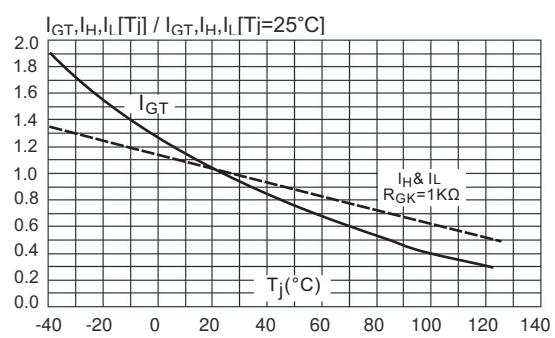


Fig.7 Relative variation of gate trigger and holding current versus junction temperature

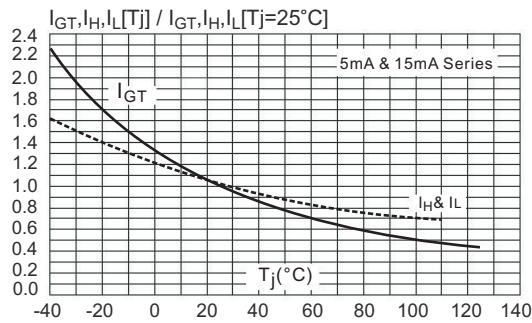


Fig.9 Relative variation of dV/dt immunity versus gate-cathode resistance (Typical values)

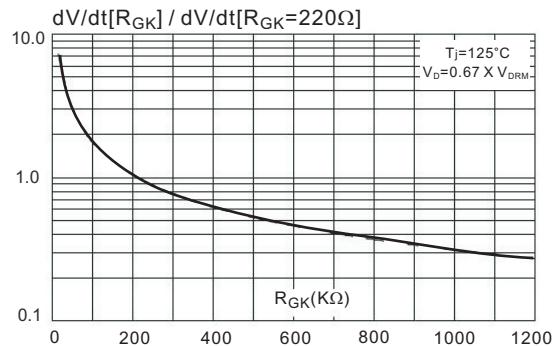


Fig.11 Surge peak on-state current versus number of cycles

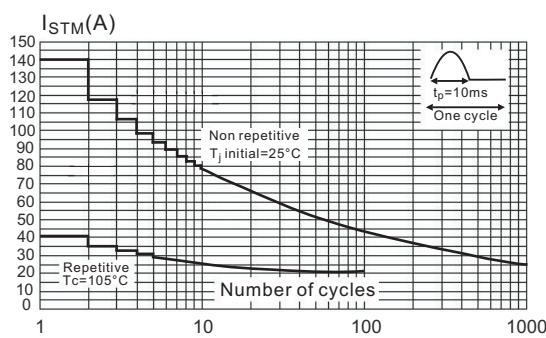


Fig.8 Relative variation of holding current versus gate-cathode resistance (typical values)

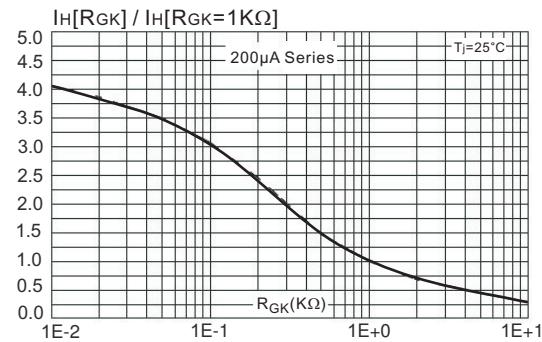


Fig.10 Relative variation of dV/dt immunity versus gate-cathode capacitance (typical values) for I_GT=200μA

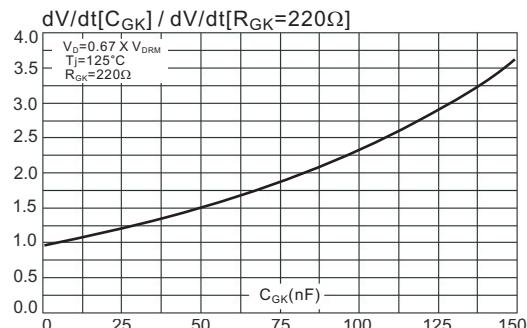


Fig.12 Non-repetitive surge peak on-state current and corresponding values of I²t versus sinusoidal pulse width

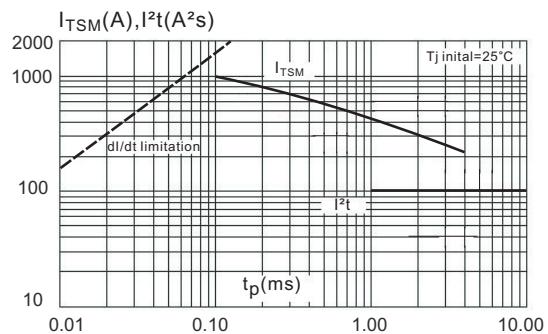


Fig.13 On-state characteristics (maximum values)

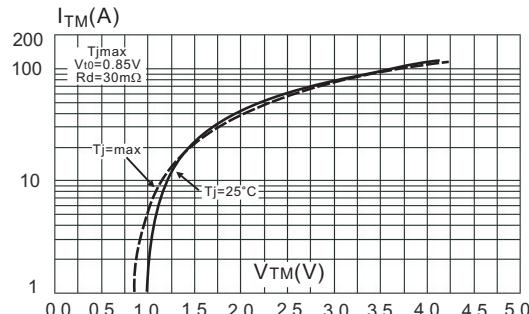
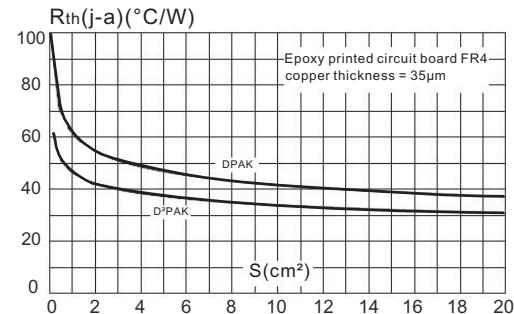
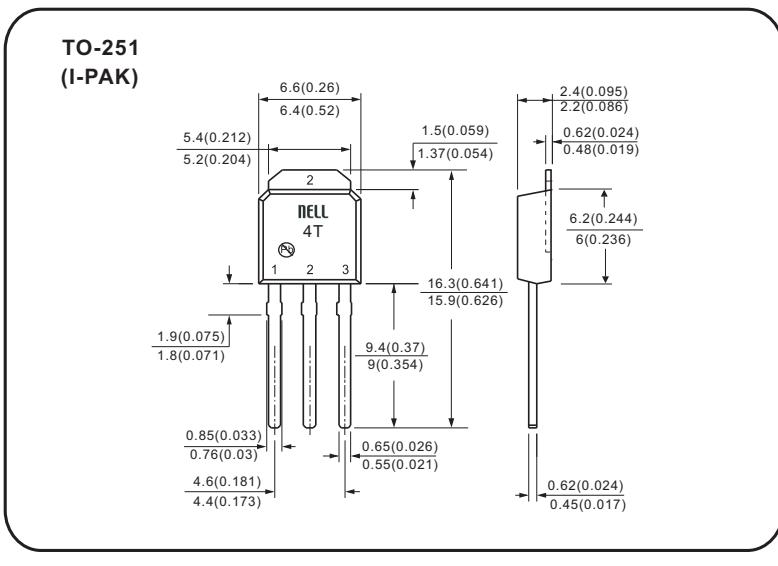
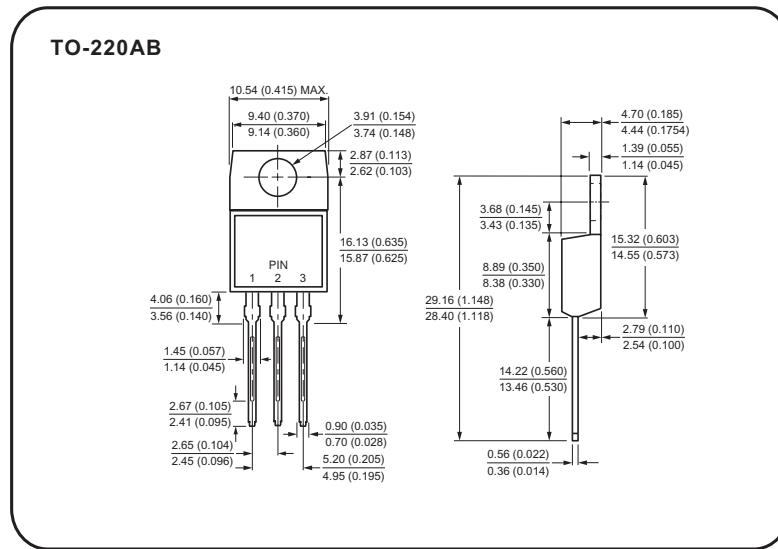


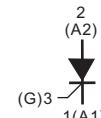
Fig.14 Thermal resistance junction to ambient versus copper surface under tab (D²PAK)



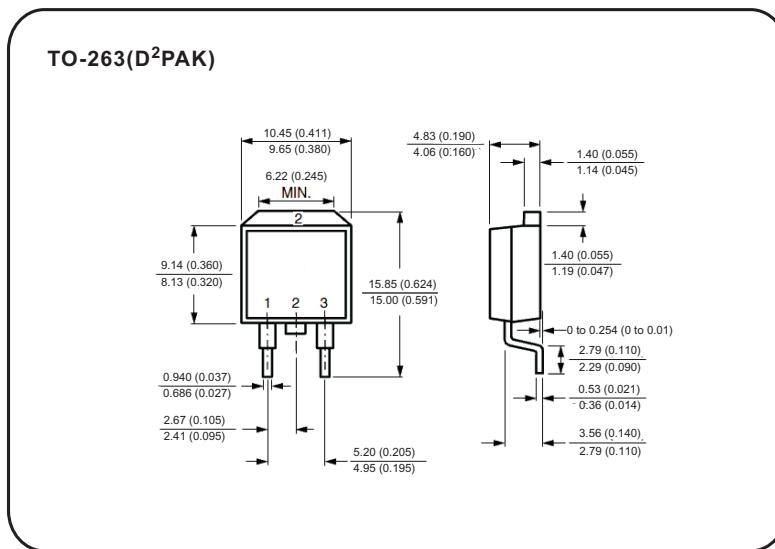
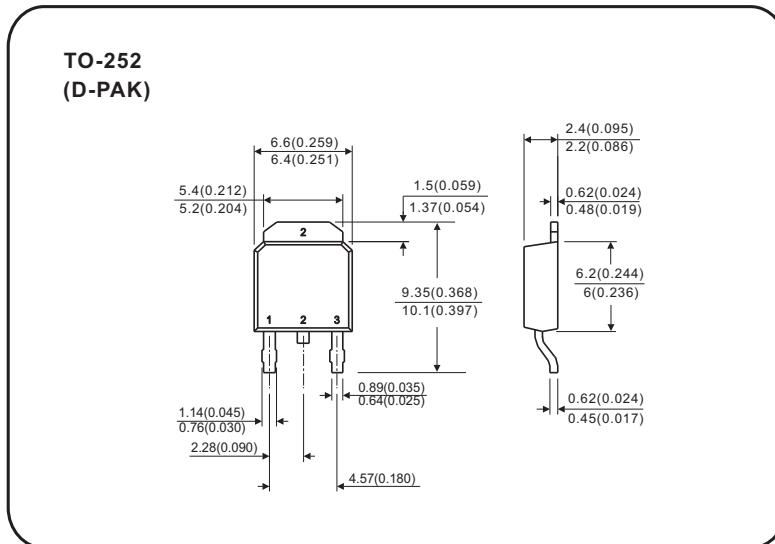
Case Style



All dimensions in millimeters (inches)



Case Style



All dimensions in millimeters(inches)

